

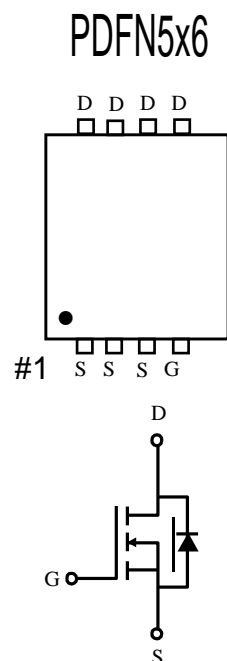
N-Channel High Density Trench MOSFET

Features:

- Super high dense cell trench design for low $R_{DS(on)}$.
- Rugged and reliable.
- Surface Mount package.

PRODUCT SUMMARY

$V_{(BR) DSS}$	$R_{DS(ON)}$	I_D
100V	8m Ω	68A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

PARAMETERS TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source voltage		V_{GS}	± 20	V
Continuous Drain current	$T_A = 25\text{ }^\circ\text{C}$	I_D	68	A
	$T_A = 100\text{ }^\circ\text{C}$		54	
Pulsed Drain Current ¹		I_{DM}	240	
Avalanche Current		I_{AS}	23	
Avalanche Energy	$L=0.1\text{mH}$	E_{AS}	26	mJ
Power Dissipation	$T_A = 25\text{ }^\circ\text{C}$	P_D	83	W
	$T_A = 100\text{ }^\circ\text{C}$		58	
Operating junction & Storage Temperature Range		T_s, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta Jc}$		1.8	$^\circ\text{C/W}$
Junction-to-Ambient	$R_{\theta JA}$		55	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS (T_A = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.6	2.3	
Gate-Body Leakage	I _{GSS}	V _{DS} =0V, V _{GS} =± 20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0 V			1	μA
		V _{DS} =80V, V _{GS} =0V, T _J =125 °C			30	
Drain-Source On- State Resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =13.5A		6.6	8	mΩ
		V _{GS} =4.5V, I _D =11.5A		8.7	10.5	
Forward Trans conductance ¹	g _{fs}	V _{DS} =5V, I _D =20A		85		S

DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =50V, f=1MHz		3320		pF
Output Capacitance	C _{oss}			605		
Reverse Transfer Capacitance	C _{rss}			20		
Gate Resistance	R _G	V _{GS} =0V, f=1MHz		3		Ω
Total Gate Charge ²	Q _{g(vgs=10V)}	V _{DS} =50V (BR)DSS, I _D = 13.5A		45		nC
	Q _{g(vgs=4.5V)}			19.3		
Gate Source Charge ²	Q _{gS(VGS=10V)}			9.5		
	Q _{gS(VGS=4.5V)}			6.5		
Gate-Drain Charge ²	Q _{gd(VGS=10V)}			4.8		
	Q _{gd(VGS=4.5V)}			2.7		
Turn-On Delay Time ²	t _{d(on)}	V _{DS} =50V, R _L =1.5Ω I _D =13.5A, V _{GS} =10V, R _{GS} =3Ω		10		nS
Rise Time ²	t _r			6.5		
Turn-Off Delay Time ²	t _{d(off)}			45		
Fall Time ²	t _f			7.5		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS(T_J=25°C)

Continuous Current	I _S			45		A
Forward Voltage ¹	V _{SD}	I _F =I _S , V _{GS} =0V		0.75	1.1	V
Reverse Recovery Time	T _{rr}	I _F =13.5A, d _I f/d _t =100A/μs		33		nS
Reverse Recovery Charge	Q _{rr}			150		nC

Note
 b. Pulse Test Pulse width ≤ 300usec , Duty Cycle ≤ 2% .
 c. Independent of operating production testing .

